

Title (en)

METAL ADHESIVE MOULDING METHOD AND THE PRODUCT MADE BY THE METHOD

Title (de)

METALLHAFTFORMVERFAHREN UND DURCH DAS VERFAHREN HERGESTELLTES PRODUKT

Title (fr)

PROCÉDÉ DE MOULAGE PAR ADHÉRENCE DE MÉTAL ET PRODUIT OBTENU AU MOYEN DE CE PROCÉDÉ

Publication

EP 2142350 A4 20130102 (EN)

Application

EP 07807931 A 20070605

Priority

- KR 2007002715 W 20070605
- KR 20070044976 A 20070509

Abstract (en)

[origin: WO2008140143A1] Provided are a metal adhesive molding method and a product made by the method, in which a metal having an adhesive coated thereon is inserted into an injection mold and synthetic resin is directly injected onto the surface of the adhesive-coated metal. The adhesive is composed of 70-80wt% polyamide, 10-20wt% petroleum resin, 2-7wt% mineral oil, and 3-7wt% amino silane. The method has the advantage of enabling a resin injection-molding product to be reliably combined with a metal having a predetermined shape. Therefore, it is possible to obtain a reliable metal adhesive molding product.

IPC 8 full level

B29C 45/14 (2006.01); **C09J 177/00** (2006.01)

CPC (source: EP KR US)

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Citation (search report)

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- [A] WO 2005109984 A2 20051124 - BANG & OLUFSEN AS [DK], et al
- [A] WO 2005061203 A2 20050707 - BOSCH GMBH ROBERT [DE], et al
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- [A] DATABASE WPI Week 199431, Derwent World Patents Index; AN 1994-252200, XP002687562
- See references of WO 2008140143A1

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DOCDB simple family (application)

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